In the Claims

Please amend the claims as follows:

1-30. (Canceled)

31. (Currently amended) The mounting socket of claim[[30]] 39 where the spring is a coil.

32. (Previously Presented) The mounting socket of claim 31 where the conductive polymer is deformable when the spring is compressed.

33. (Currently amended) The mounting socket of claim[[30]] 39 where the vias have a constant width.

34. (Currently amended) The mounting socket of claim[[30]] where the conductive polymer fills the vias from side to side.

35. (Previously Presented) The mounting socket of claim 34 where the conductive polymer fills the vias from end to end.

36. (Currently amended) The mounting socket of claim[[30]] 39 where the terminals extend beyond the first and second sides of the body.

37. (Currently amended) The mounting socket of claim[[30]] 39 where the terminals are solderless.

38. (Canceled)

39. (Currently amended) ~~The mounting socket of claim 38 further comprising:~~ A mounting socket, comprising:

a body having first and second sides, and having a plurality of vias extending from a first side to a second side;

a plurality of conductive terminals within the vias, each terminal including

a spring extending through one of the vias and adapted to exert a return force when compressed,

a conductive polymer in contact with the spring and with the one via;

a first adhesive layer affixed to the first side of the body;

a polymer tape applied to the first adhesive layer;

a ground and power line circuit on the polymer tape.

40. (Previously Presented) The mounting socket of claim 39 further comprising a second adhesive layer applied over the ground and power line circuit.

41. (Currently amended) The mounting socket of claim[[30]] 39 further comprising a further adhesive layer affixed to the second side of the body.

42. (Canceled).

43. (Currently amended) The circuit assembly of claim[[42]] 44 where the conductive terminals exert a force upon the lands.

44. (Currently amended) ~~The circuit assembly of claim 42 further comprising~~ A circuit assembly, comprising:

a substrate having a plurality of lands thereon;

a socket body having a first side in contact with the substrate, and having an opposite side;

a plurality of vias extending from the first side to the opposite side;

a plurality of conductive terminals within the vias and contacting the lands, each terminal including

a spring extending through one of the vias and adapted to exert a return force when compressed,

a conductive polymer in contact with the spring and with the one via;

an adhesive layer bonding the socket body to the substrate;

a polymer tape applied to the adhesive layer;

a ground and power line circuit on the polymer tape.

45. (Currently amended) The circuit assembly of claim[[42]] 44 further comprising an integrated circuit coupled to the substrate.

46. (Previously Presented) The circuit assembly of claim 45 further comprising a circuit board contacting the opposite side of the socket body.

47. (Previously Presented) The circuit assembly of claim 46 further comprising another adhesive layer on the opposite side of the socket body bonding it to the circuit board.

48-56. (Canceled)